US0D1089808S

(12) United States Design Patent

Sakurai et al.

(10) Patent No.: US D1,089,808 S
(45) Date of Patent: ** Aug. 19, 2025

(54) **LIGHT-EMITTING ELEMENT MODULE**

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(**) Term: **15 Years**

(21) Appl. No.: **29/798,752**

(22) Filed: **Jul. 9, 2021**

(30) **Foreign Application Priority Data**

Jan. 20, 2021 (JP) ..... 2021-001097 D
Jan. 20, 2021 (JP) ..... 2021-001098 D

(51) **LOC (15) Cl.** **26-05**

(52) **U.S. Cl.**
USPC **D26/120**

(58) **Field of Classification Search**
USPC D26/1, 2, 35, 120; D13/180, 181
CPC H01L 33/00; H01L 33/04; H01L 33/08; H01L 33/10; H01L 33/20; H01L 33/38; H01L 33/42; H01L 25/167; H01L 25/0753; H01L 27/0248; H01L 27/15; H01L 27/156; F21S 43/00; H10H 20/80; H10H 20/811; H10H 20/813; H10H 20/814; H10H 20/819; H10H 20/831; H10H 20/833; H10H 29/14; H10H 29/142; H10D 84/60
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a light-emitting element module as shown and described.

DESCRIPTION

FIG. **1** is a front view of a light-emitting element module of the first embodiment of the present invention;
FIG. **2** is a rear view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a left side view thereof;
FIG. **7** is a front, top and right side perspective view thereof;
FIG. **8** is a rear, bottom and left side perspective view thereof;
FIG. **9** is a sectional view thereof with inner mechanism is omitted taken along the line **9-9** in FIG. **3**;
FIG. **10** is an enlarged view thereof defined by the line **10-10** in FIG. **7**;
FIG. **11** is an enlarged sectional view thereof with inner mechanism is omitted defined by the line **11-11** in FIG. **9**;
FIG. **12** is a front view of a light-emitting element module of the second embodiment of the present invention;
FIG. **13** is a rear view thereof;
FIG. **14** is a top plan view thereof;
FIG. **15** is a bottom plan view thereof;
FIG. **16** is a right side view thereof;
FIG. **17** is a left side view thereof;
FIG. **18** is a front, top and right side perspective view thereof;
FIG. **19** is a rear, bottom and left side perspective view thereof;
FIG. **20** is a sectional view thereof with inner mechanism is omitted taken along the line **20-20** in FIG. **14**;
(Continued)

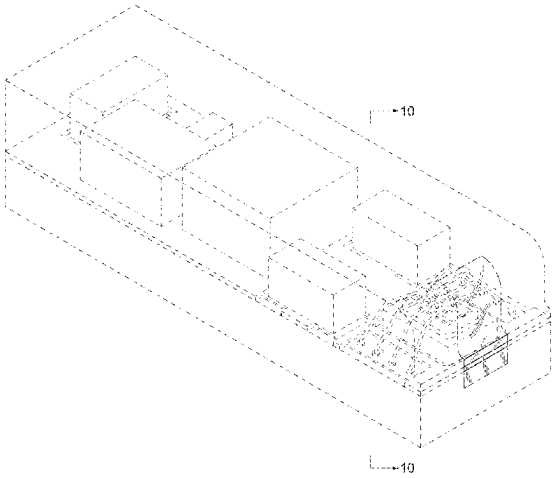

FIG. **21** is an enlarged view thereof defined by the line **21-21** in FIG. **18**; and,

FIG. **22** is an enlarged sectional view thereof with inner mechanism is omitted defined by the line **22-22** in FIG. **20**.

The broken lines show portions of a light-emitting element module that form no part of the claimed design.

The alternate long and short dash lines are merely the boundary lines between the claimed parts and the non-claimed parts.

1 Claim, 22 Drawing Sheets

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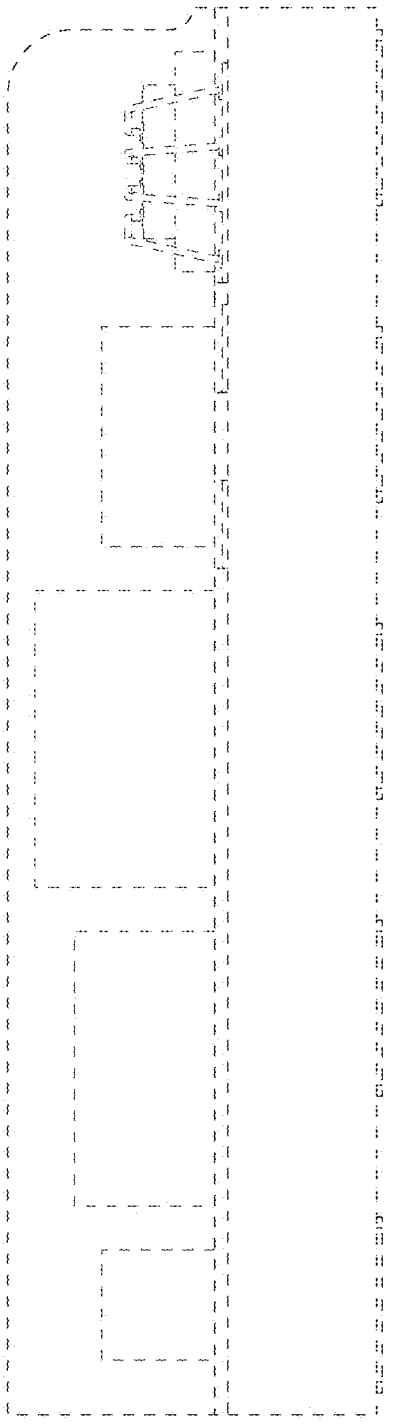

FIG. 1

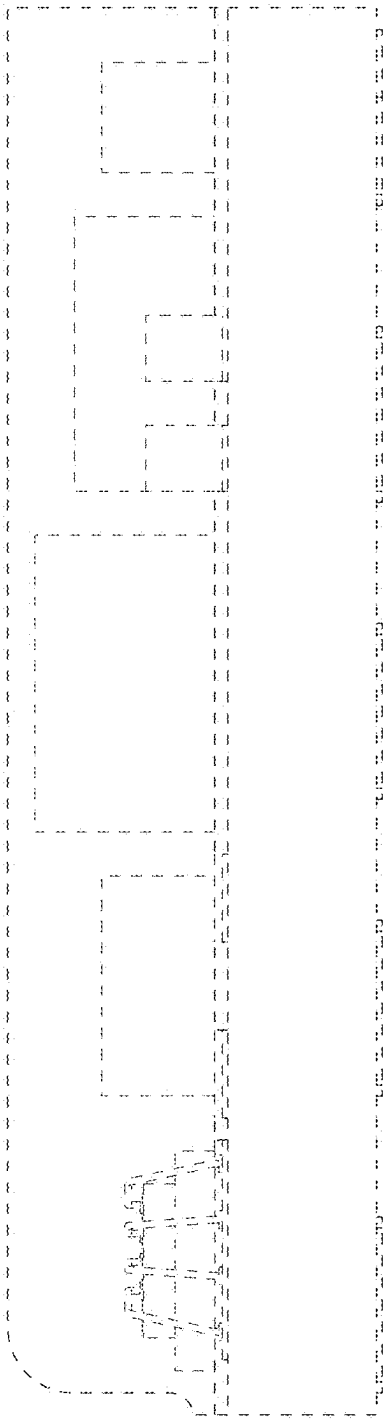

FIG. 2

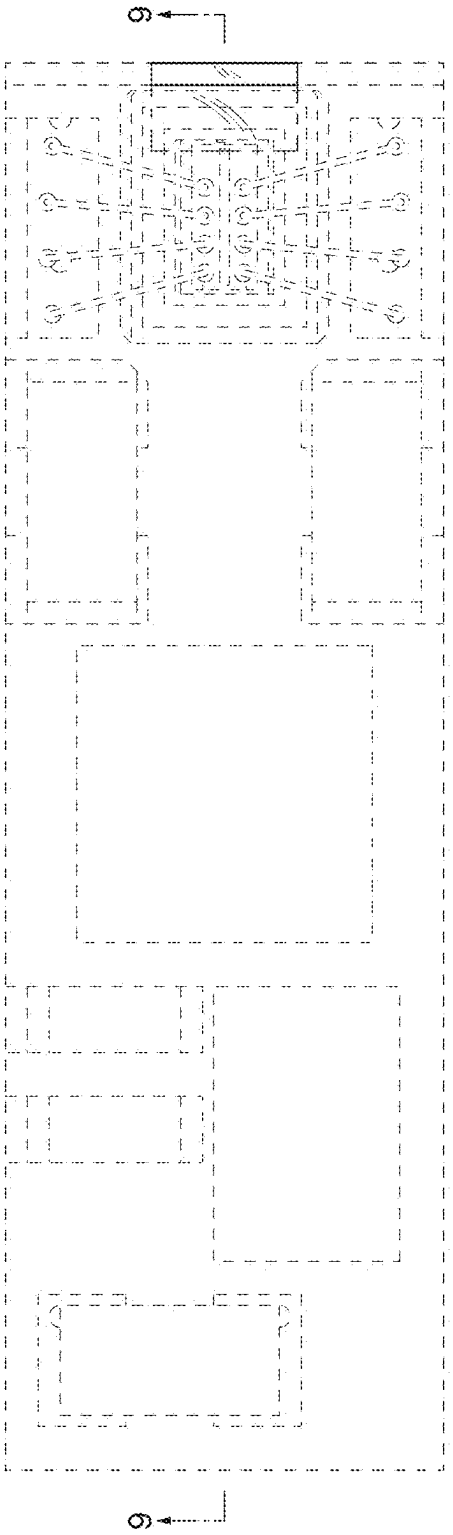

FIG. 3

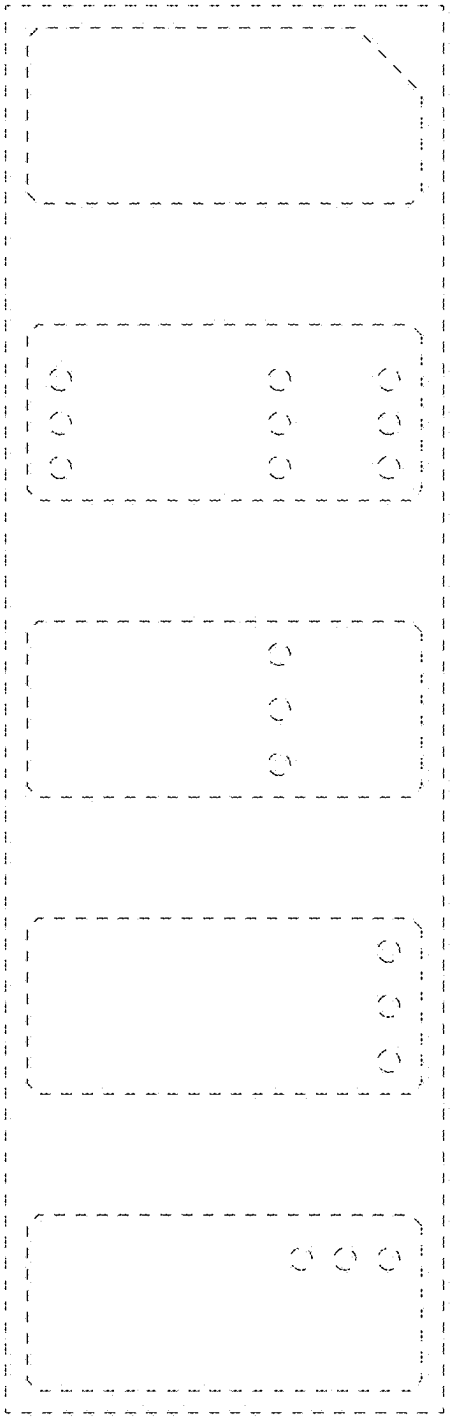

FIG. 4

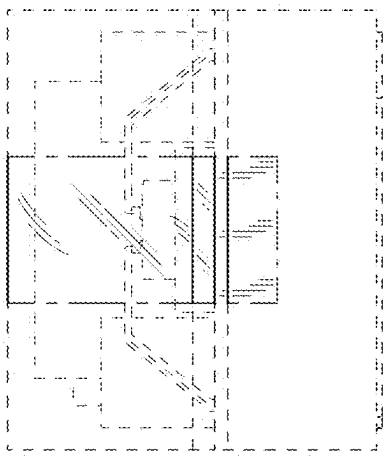

FIG. 5

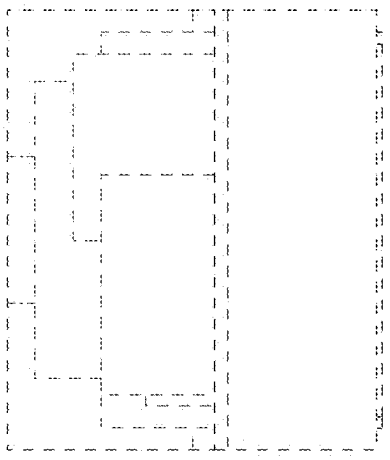

FIG. 6

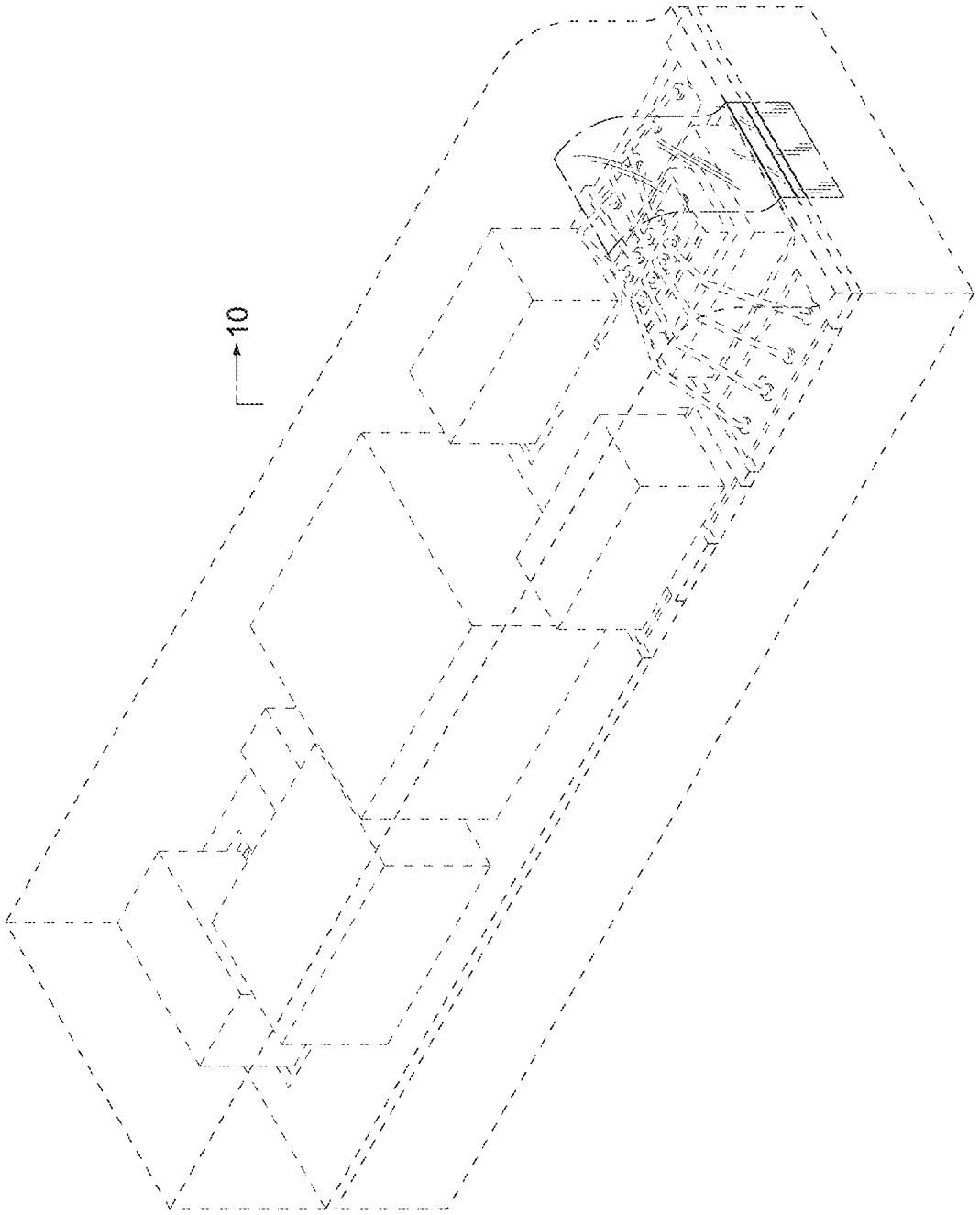

FIG. 7

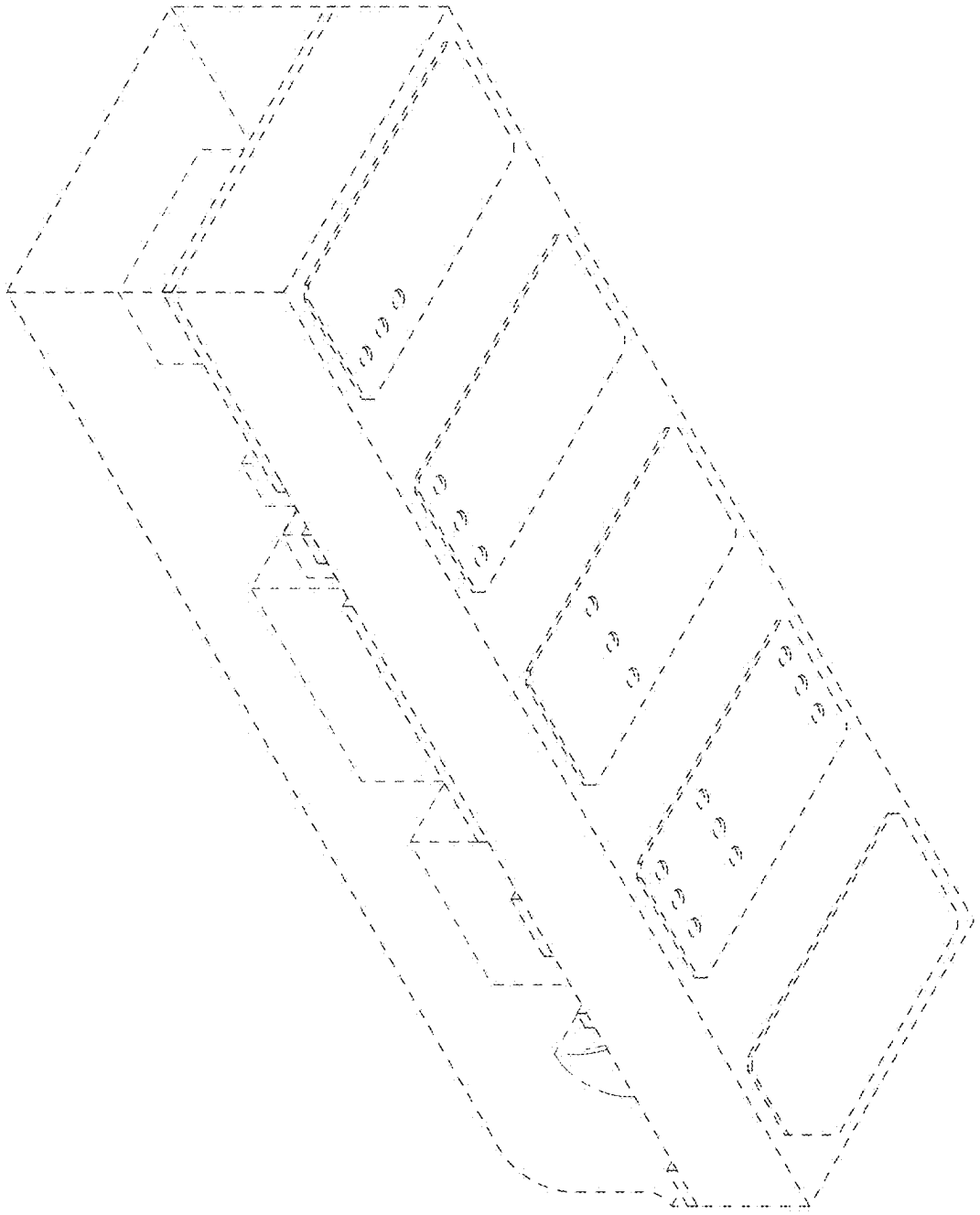

FIG. 8

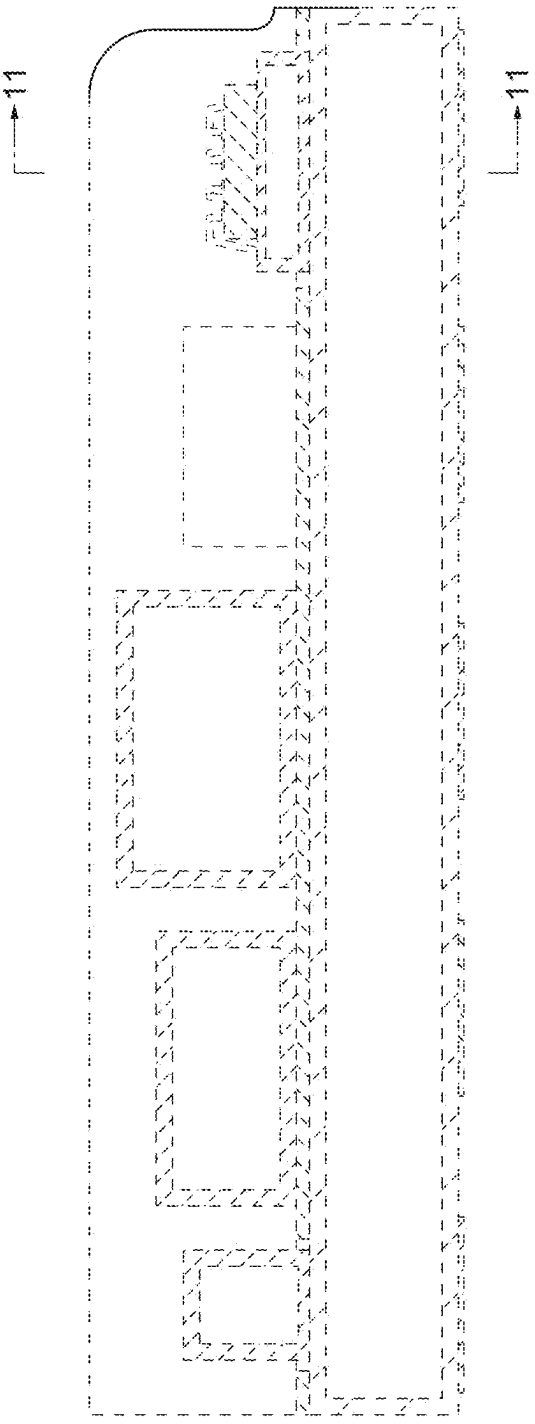

FIG. 9

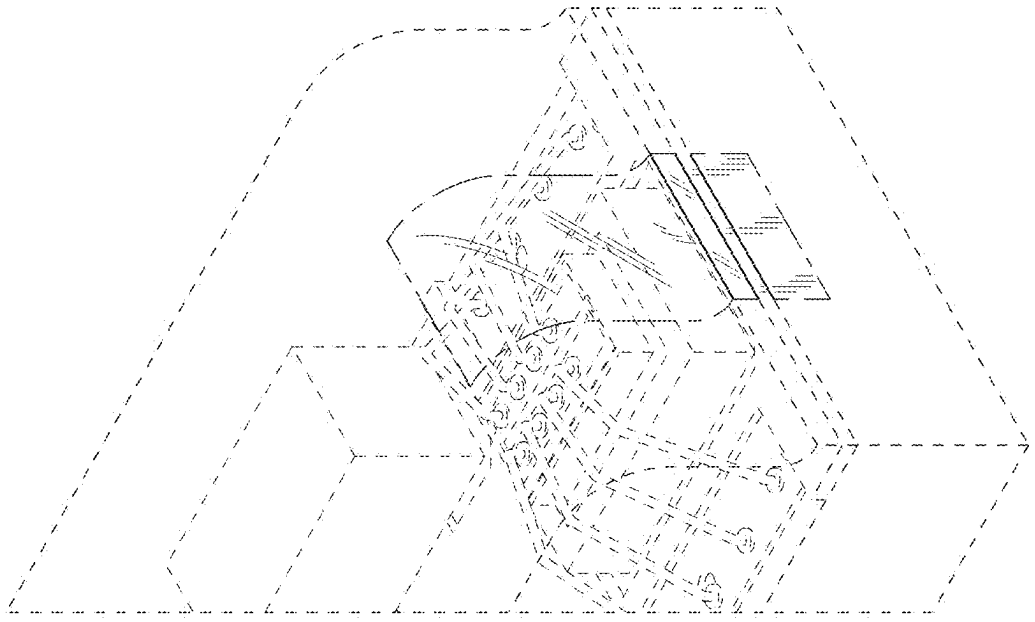

FIG. 10

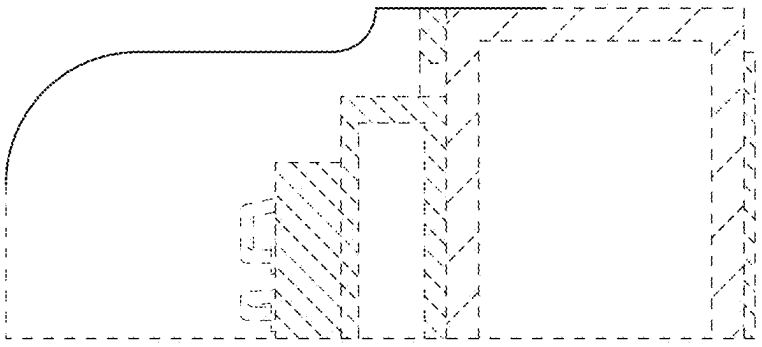

FIG. 11

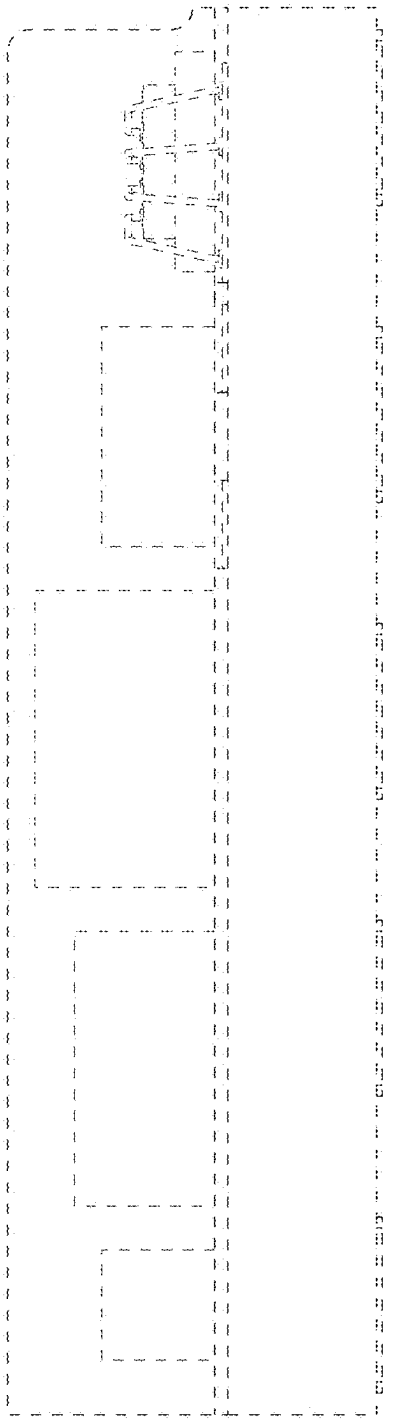

FIG. 12

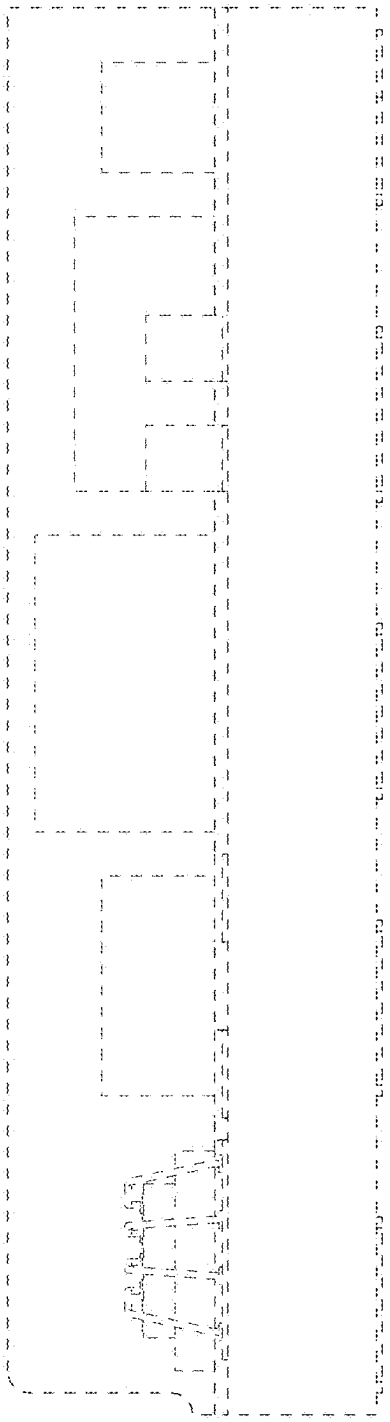

FIG. 13

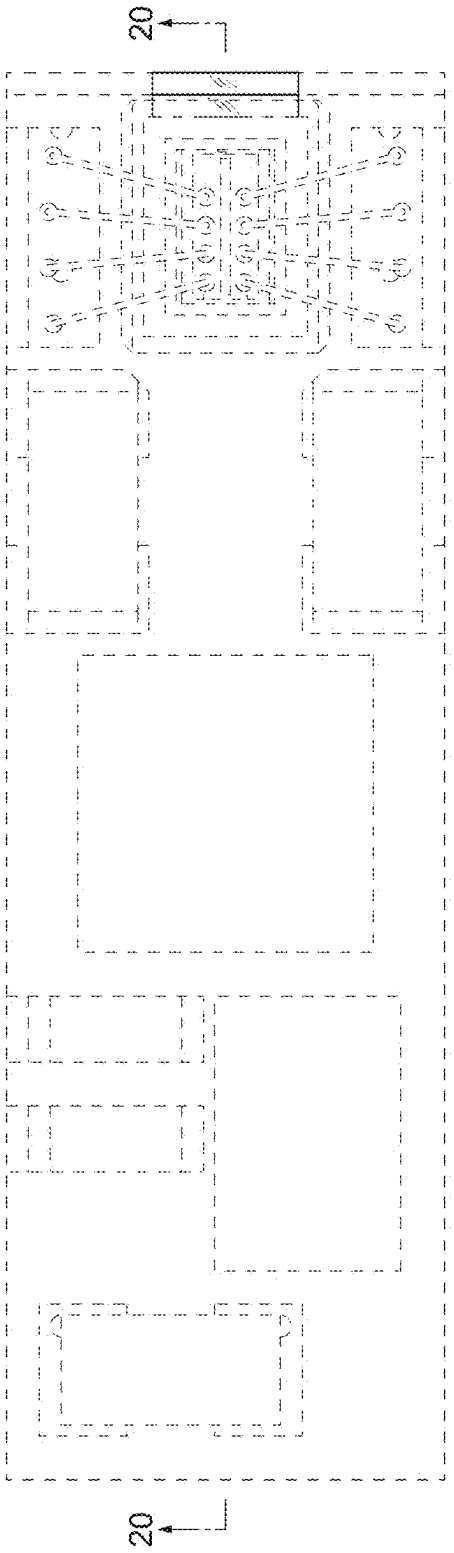

FIG. 14

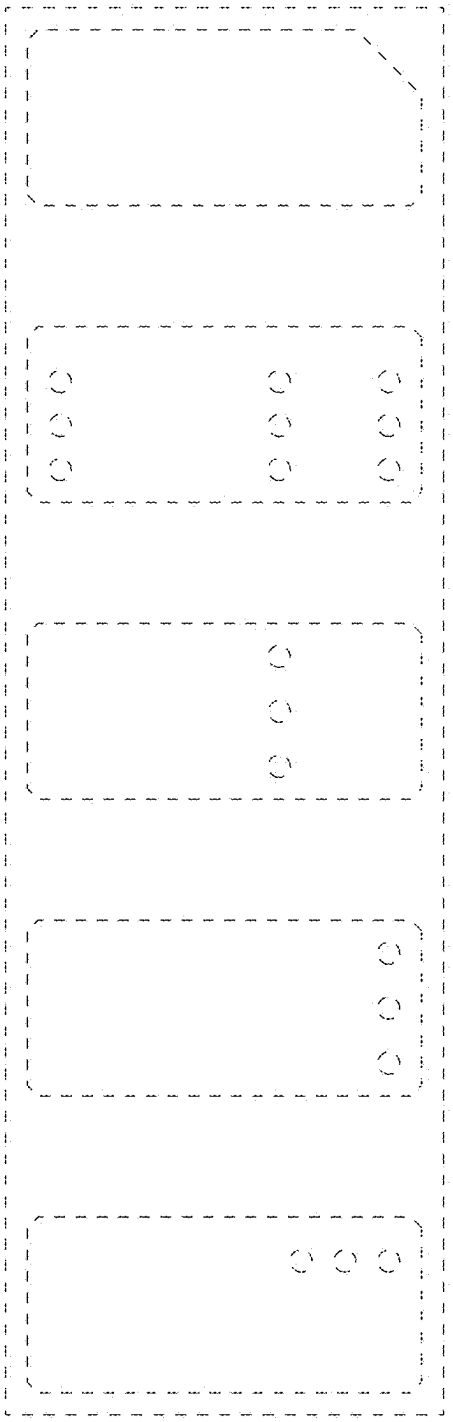

FIG. 15

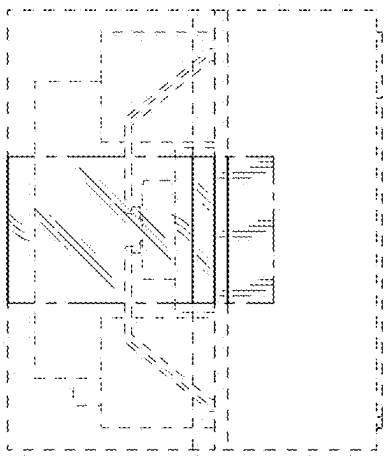

FIG. 16

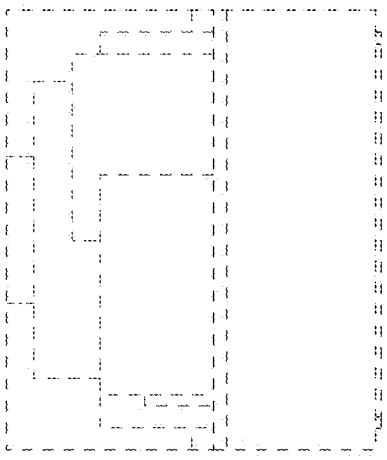

FIG. 17

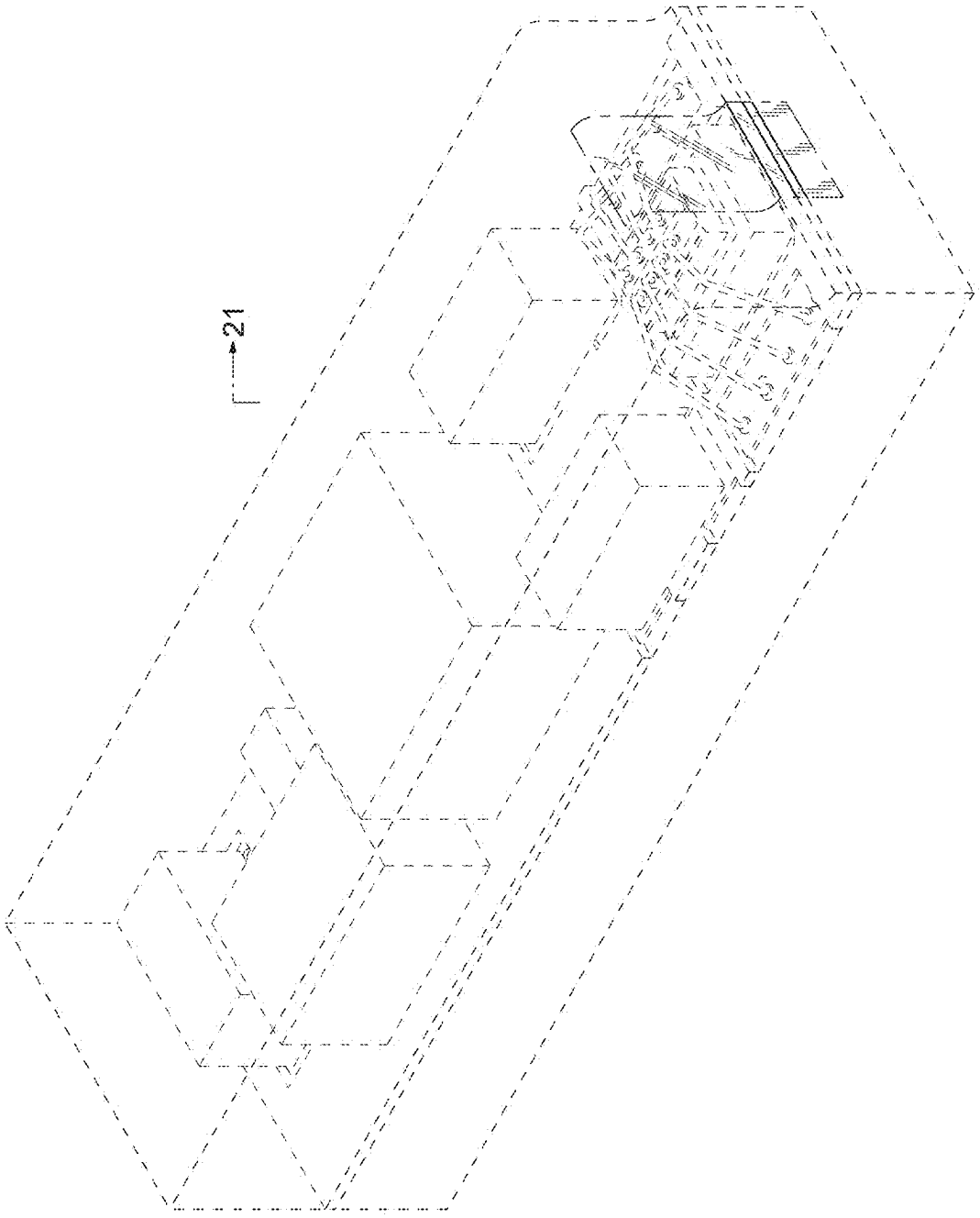

FIG. 18

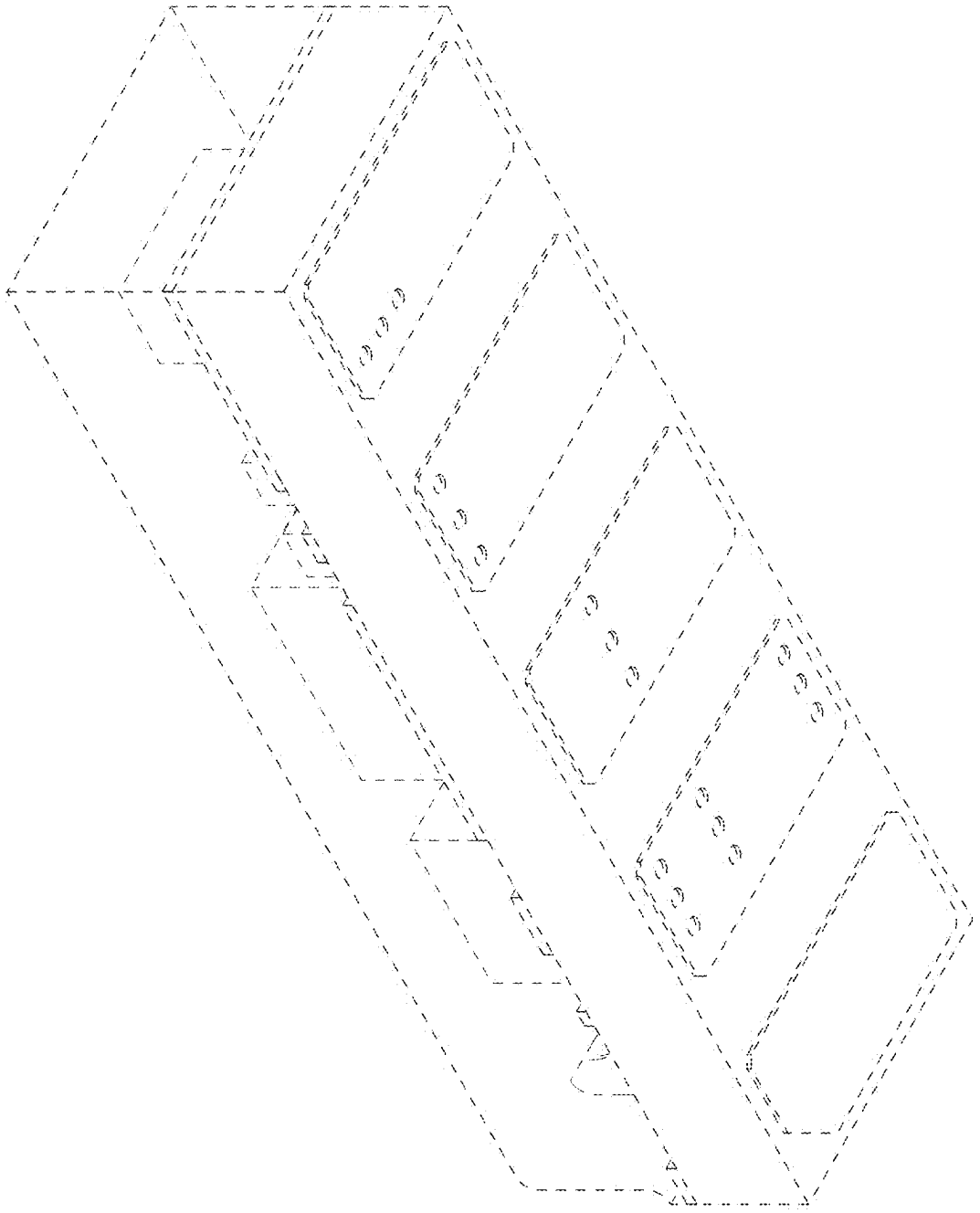

FIG. 19

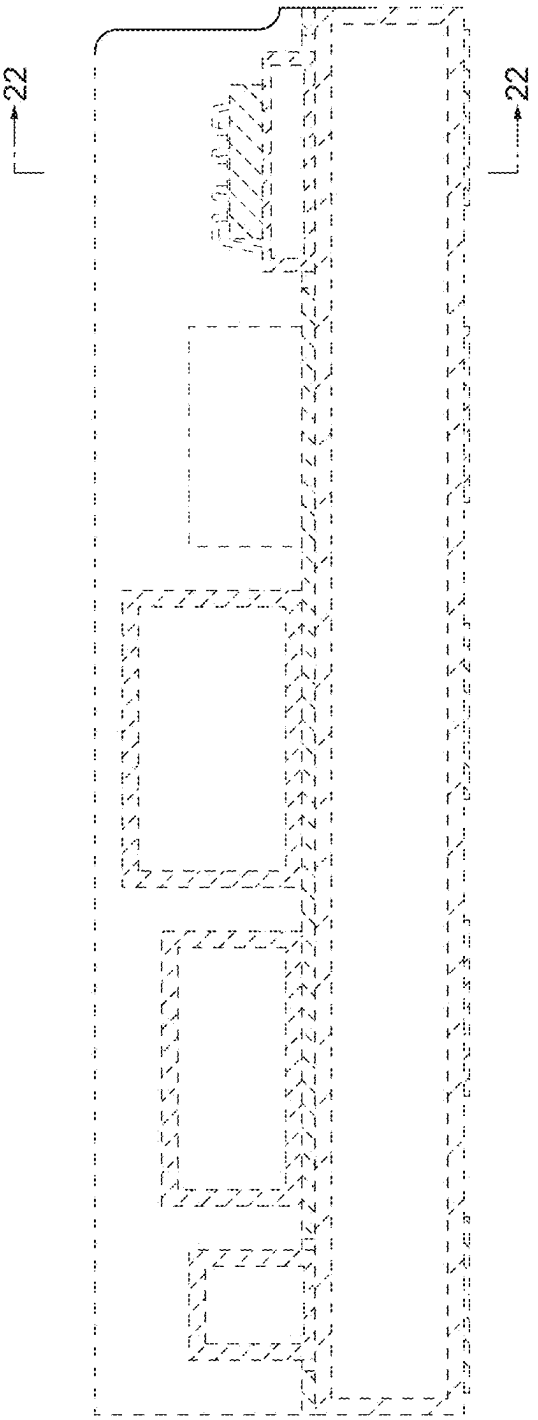

FIG. 20

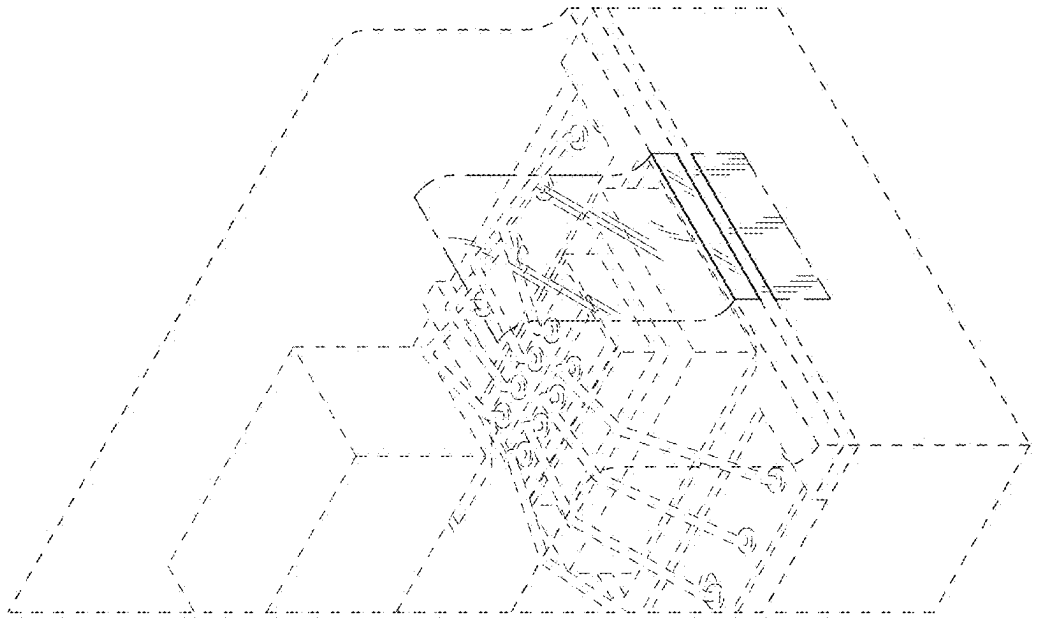

FIG. 21

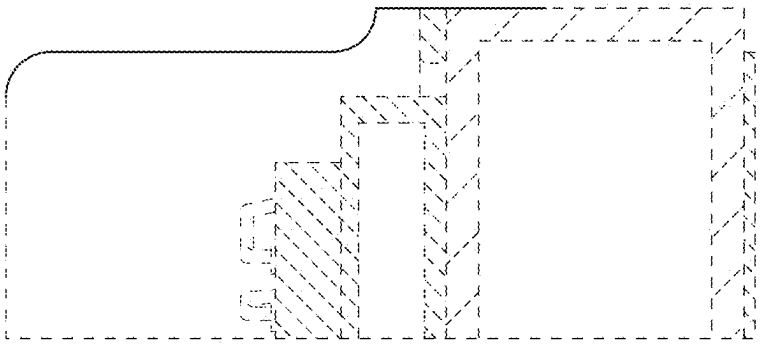

FIG. 22